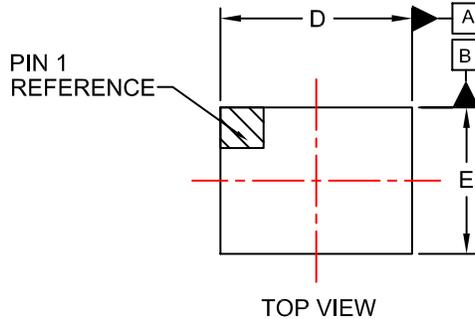


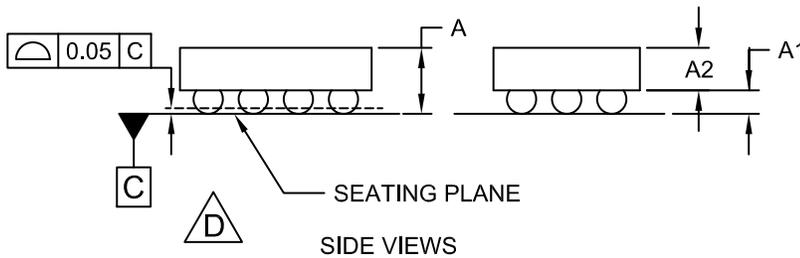
WLCSP12 1.828x1.288x0.574
CASE 567WP
ISSUE O

DATE 25 JUN 2018

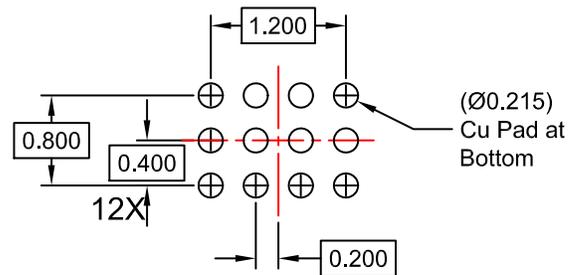
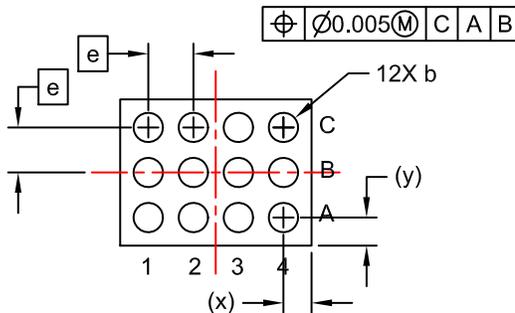


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.536	0.574	0.612
A1	0.176	0.196	0.216
A2	0.360	0.378	0.396
b	0.240	0.260	0.280
D	1.798	1.828	1.858
E	1.258	1.288	1.318
e	0.40 BSC		
x	0.299	0.314	0.329
y	0.229	0.244	0.259



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DESCRIPTION:	WLCSP12 1.828x1.288x0.574	PAGE 1 OF 1

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